SLOVENSKI STANDARD
SIST EN IEC 61760-2:2021

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Nadomešča:
SIST EN 61760-2:2007

Tehnologija površinske montaže - 2. del: Pogoji pri prevažanju in shranjevanju sestavov za površinsko montažo (SMD) - Vodilo za uporabo

Surface mounting technology - Part 2: Transportation and storage conditions of surface mounting devices (SMD) - Application guide

Oberflächenmontagetechnik - Teil 2: Transport- und Lagerungsbedingungen von oberflächenmontierbaren Bauelementen (SMD) - Anwendungsleitfaden

Technique du montage en surface - Partie 2: Conditions de transport et de stockage des composants pour montage en surface (CMS) - Guide d'application

Ta slovenski standard je istoveten z: **EN IEC 61760-2:2021**

ICS:

31.020	Elektronske komponente na splošno	Electronic components in general

SIST EN IEC 61760-2:2021 **en**

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 61760-2

September 2021

ICS 31.240

Supersedes EN 61760-2:2007 and all of its amendments and corrigenda (if any)

English Version

Surface mounting technology - Part 2: Transportation and storage conditions of surface mounting devices (SMD) - Application guide (IEC 61760-2:2021)

Technique du montage en surface - Partie 2: Conditions de transport et de stockage des composants pour montage en surface (CMS) - Guide d'application
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Oberflächenmontagetechnik - Teil 2: Transport- und Lagerungsbedingungen von oberflächenmontierbaren Bauelementen (SMD) - Anwendungsleitfaden
(IEC 61760-2:2021)

This European Standard was approved by CENELEC on 2021-08-20. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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CENELEC
European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

Ref. No. EN IEC 61760-2:2021 E

European foreword

The text of document 91/1666/CDV, future edition 3 of IEC 61760-2, prepared by IEC/TC 91 “Electronics assembly technology” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61760-2:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022–05–20
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024–08–20

This document supersedes EN 61760-2:2007 and all of its amendments and corrigenda (if any).

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

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Endorsement notice

The text of the International Standard IEC 61760-2:2021 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60286-3	NOTE Harmonized as EN IEC 60286-3
IEC 60286-4	NOTE Harmonized as EN 60286-4
IEC 60286-5	NOTE Harmonized as EN IEC 60286-5
IEC 60286-6	NOTE Harmonized as EN 60286-6
IEC 60749 (series)	NOTE Harmonized as EN 60749 (series)
IEC 60749-20-1:2019	NOTE Harmonized as EN IEC 60749-20-1:—[1] (not modified)
IEC 61340-5-1	NOTE Harmonized as EN 61340-5-1
IEC 61760-4:2015	NOTE Harmonized as EN 61760-4:2015 (not modified)
IEC 62435 (series)	NOTE Harmonized as EN IEC 62435 (series)

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[1] To be published. Stage at the time of publication: prEN IEC 60749-20-1:2019.

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60721-3-1	2018	Classification of environmental conditions - Part 3–1: Classification of groups of environmental parameters and their severities - Storage	EN IEC 60721-3-1	2018
IEC 60721-3-2	2018	Classification of environmental conditions - Part 3–2: Classification of groups of environmental parameters and their severities - Transportation and handling	EN IEC 60721-3-2	2018

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INTERNATIONAL STANDARD

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inside

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CONTENTS

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SURFACE MOUNTING TECHNOLOGY –

Part 2: Transportation and storage conditions of surface mounting devices (SMD) – Application guide

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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IEC 61760-2 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1666/CDV	91/1708/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

Cross-references for references from this edition 3 to the previous edition 2 of this document are listed in Annex X of this document.

A list of all parts in the IEC 61760 series, published under the general title *Surface mounting technology*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

SURFACE MOUNTING TECHNOLOGY –

Part 2: Transportation and storage conditions of surface mounting devices (SMD) – Application guide

1 Scope

This International Standard specifies the transportation and storage conditions for surface mounting devices (SMDs) that are fulfilled in order to enable trouble-free processing of surface mounting devices, both active and passive. (Conditions for printed boards are not taken into consideration.)

The object of this document is to ensure that users of SMDs receive and store products that can be further processed (e.g. positioned, soldered) without prejudice to quality and reliability. Improper transportation and storage of SMDs can cause deterioration and result in assembly problems such as poor solderability, delamination and "popcorning".

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60721-3-1:2018, *Classification of environmental conditions – Part 3-1: Classification of groups of environmental parameters and their severities – Storage*

IEC 60721-3-2:2018, *Classification of environmental conditions – Part 3-2: Classification of groups of environmental parameters and their severities – Transportation and handling*

3 Terms and definitions

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

No terms and definitions are listed in this document.

4 General conditions

Surface mounting devices shall be packed in such a way that products are protected during transportation and storage without loss of their properties arising from mechanical, environmental and electrical influences. Packing requirements as defined in various IEC publications, such as IEC 60286-3, IEC 60286-4, IEC 60286-5, IEC 60286-6 and IEC TR 61340-5-5 can contribute to the protection of components during transportation and storage.

If dry packing is specified and used, the IEC publications IEC 61760-4, IEC 60749-20-1 and IPC/JEDEC J-STD-033 should be consulted.